Product Summary

BV_{DSS}	$R_{D1D2(ON)\ TYP}$	I_{D1D2} T_A = +25°C
-20V	82mΩ @ V_{GS} = -4.5V	-3.0A

Description

This new generation MOSFET has been designed to minimize the on-state resistance ($R_{D1D2(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Battery Management
- Load Switch
- Battery Protection

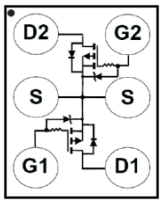
Features and Benefits

- Low Q_g & Q_{gd}
- Dual PMOS in Common-Source Configuration
- Small Footprint 1.5mm × 1.0mm
- **Gate ESD Protection to 6kV**
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Mechanical Data

- Case: U-WLB1510-6
- Terminal Connections: See Diagram Below
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal: Finish - SnAgCu. Solderable per MIL-STD-202 Method 208 e1
- UBM Opening: 280µm

U-WLB1510-6 (Type B)



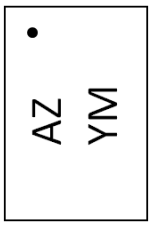
Top View

Ordering Information (Note 4)

Part Number	Case	Packaging
DMP2108UCB6-7	U-WLB1510-6 (Type B)	3000/Tape & Reel

Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



AZ= Product Type Marking Code
YM = Date Code Marking
Y = Year (ex: G = 2019)
M = Month (ex: N = November)

Date Code Key

Year	2019	2020	2021	2022	2023	2024	2025
Code	G	H	I	J	K	L	M

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DS}	-20	V
Gate-Source Voltage			V_{GS}	-6	V
Continuous Drain Current (Note 5) V_{GS} = -4.5V	Steady State	T_A = +25°C T_A = +70°C	I_{D1D2}	-2.25 -1.8	A
Continuous Drain Current (Note 6) V_{GS} = -4.5V	Steady State	T_A = +25°C T_A = +70°C	I_{D1D2}	-3.0 -2.4	A
Continuous Source Pin Current (Note 6)			I_S	-2.0	A
Continuous Gate Clamp Current (Note 6)			I_G	-0.5	A
Pulsed Source Pin Current (Pulse Duration 10µs, Duty Cycle ≤ 1%)			I_{SM}	-39	A
Pulsed Gate Clamp Current (Pulse Duration 10µs, Duty Cycle ≤ 1%)			I_{GM}	-7	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P_D	0.84	W
Total Power Dissipation (Note 6)	P_D	1.2	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	152.7	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	105.4	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	-20	—	—	V	V_{GS} = 0V, I_{DS} = -250µA
Zero Gate Voltage Drain Current @T_C = +25°C	I_{DSS}	—	—	-1	µA	V_{DS} = -16V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	-100	nA	V_{GS} = -6V, V_{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(TH)}$	-0.5	-0.75	-1.1	V	V_{DS} = V_{GS}, I_{DS} = -250µA
Static Drain-Source On-Resistance	$R_{D1D2(ON)}$	—	82	100	mΩ	V_{GS} = -4.5V, I_{D1D2} = -1A
		—	110	150		V_{GS} = -2.5V, I_{D1D2} = -1A
		—	160	240		V_{GS} = -1.8V, I_{D1D2} = -1A
	$R_{DS(ON)}$	—	42	55	mΩ	V_{GS} = -4.5V, I_{DS} = -1A
		—	56	80		V_{GS} = -2.5V, I_{DS} = -1A
		—	80	120		V_{GS} = -1.8V, I_{DS} = -1A
DIODE CHARACTERISTICS						
Diode Forward Voltage (Note 6)	V_{SD}	—	-0.72	-1	V	V_{GS} = 0V, I_{DS} = -1A
Reverse Recovery Charge	Q_{RR}	—	2.3	—	nC	V_{DD} = -10V, I_F = -1A, di/dt = 200A/µs
Reverse Recovery Time	t_{RR}	—	7.1	—	ns	
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C_{iss}	—	269	—	pF	V_{DS} = -10V, V_{GS} = 0V, f = 1.0MHz
Output Capacitance	C_{oss}	—	142	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	7.6	—	pF	
Total Gate Charge (-4.5V)	Q_g	—	2.1	—	nC	V_{GS} = -4.5V, V_{DS} = -10V, I_{DS} = -1A
Gate-Source Charge	Q_{gs}	—	0.3	—	nC	
Gate-Drain Charge	Q_{gd}	—	0.3	—	nC	
Gate Charge at V_{TH}	$Q_{g(TH)}$	—	0.16	—	nC	
Turn-On Delay Time	$t_{D(ON)}$	—	6	—	ns	V_{DD} = -10V, V_{GS} = -4.5V, I_{DS} = -1A, R_G = 30Ω
Turn-On Rise Time	t_R	—	7	—	ns	
Turn-Off Delay Time	$t_{D(OFF)}$	—	34	—	ns	
Turn-Off Fall Time	t_F	—	16	—	ns	

Notes:
5. Device mounted on FR-4 PCB with minimum recommended pad layout.
6. Device mounted on FR-4 material with 1 inch^2 (6.45cm^2), 2 oz. (0.071mm thick) Cu.
7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to production testing.

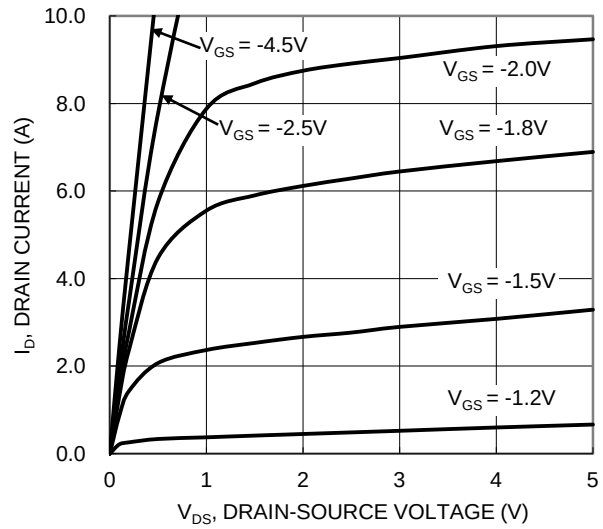


Figure 1.Typical Output Characteristic

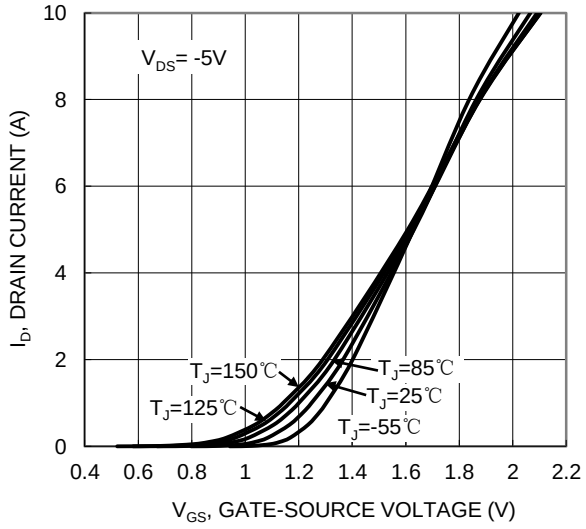


Figure 2. Typical Transfer Characteristic

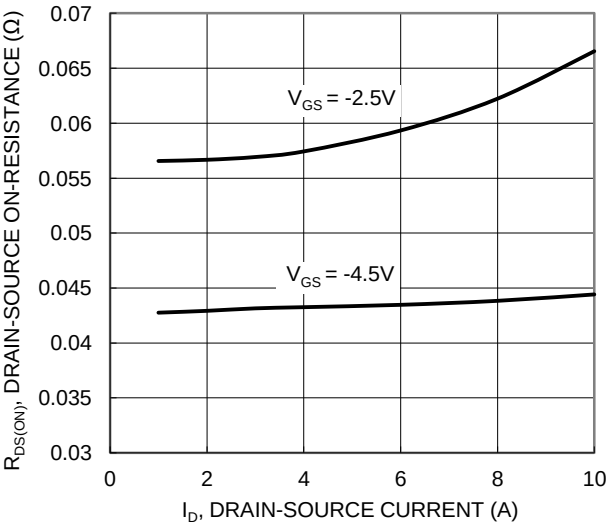


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

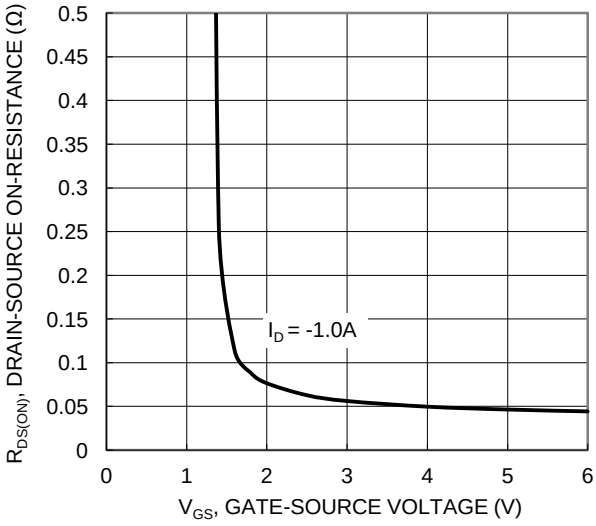


Figure 4. Typical Transfer Characteristic

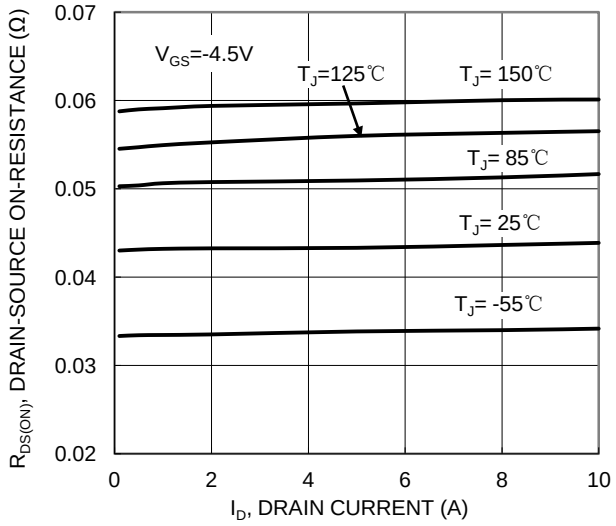


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

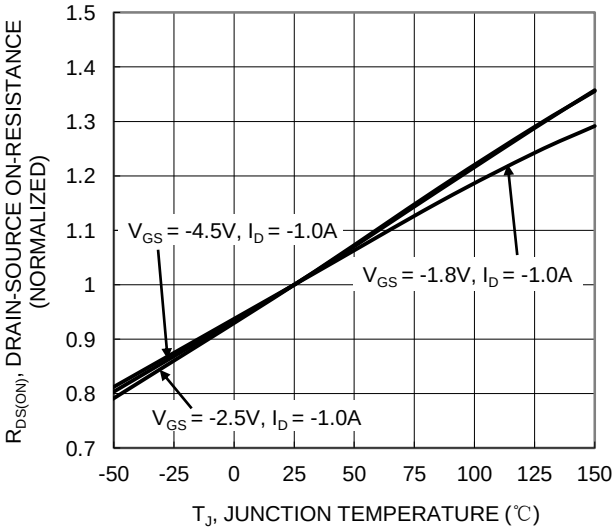


Figure 6. On-Resistance Variation with Junction Temperature

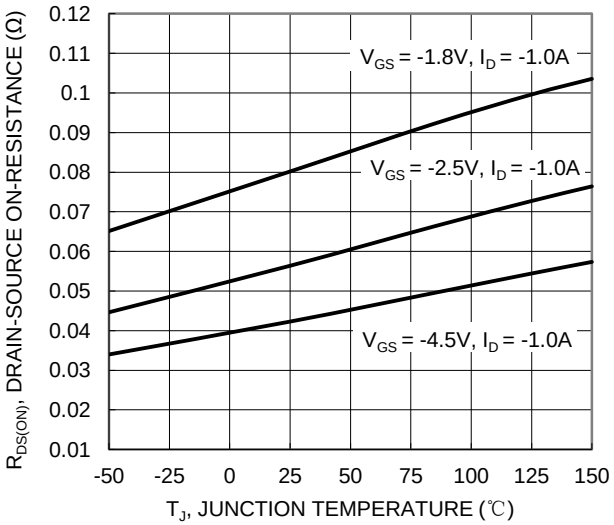


Figure 7. On-Resistance Variation with Junction Temperature

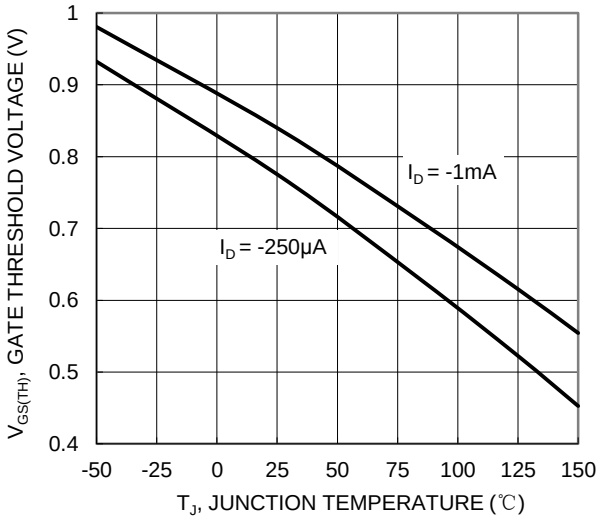


Figure 8. Gate Threshold Variation vs. Junction Temperature

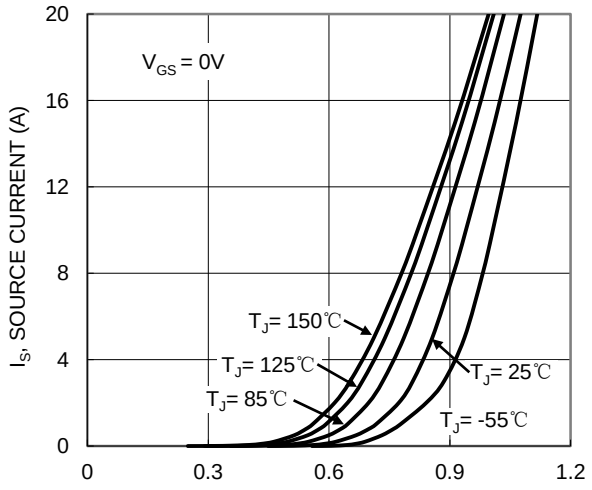


Figure 9. Diode Forward Voltage vs. Current

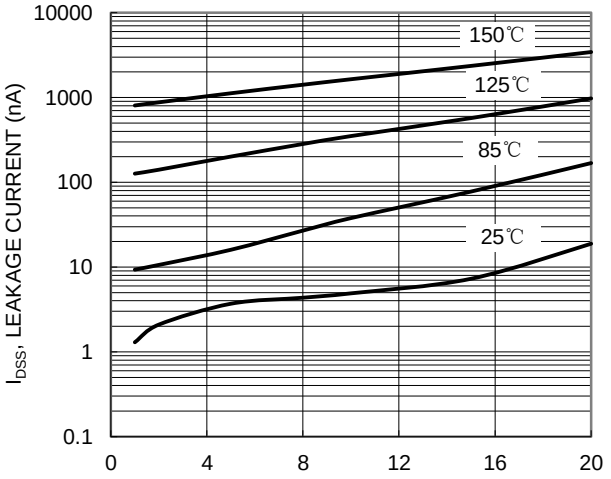


Figure 10. Typical Drain-Source Leakage Current vs. Voltage

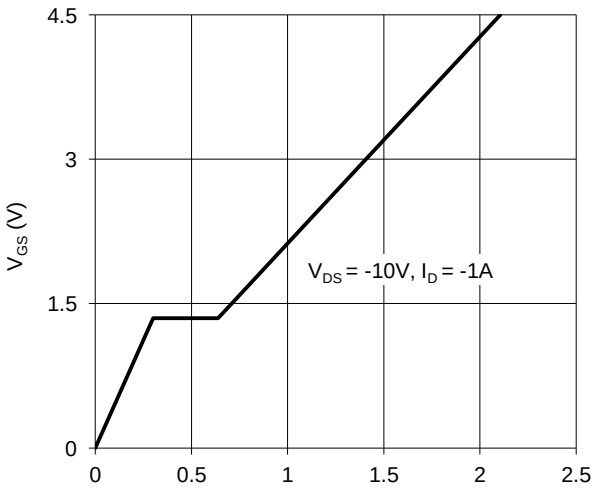


Figure 11. Gate Charge

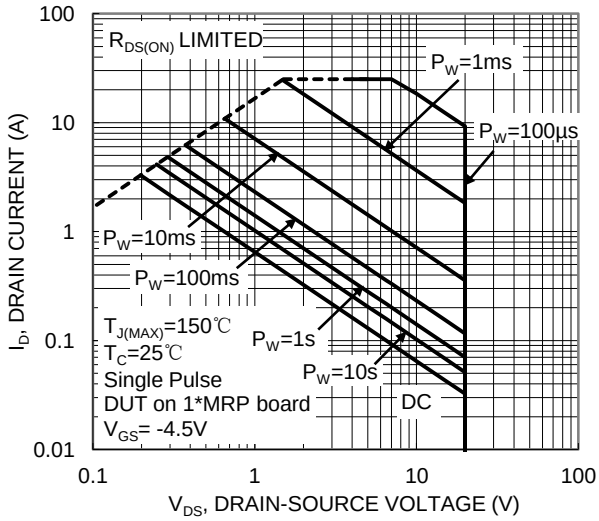


Figure 12. SOA, Safe Operation Area

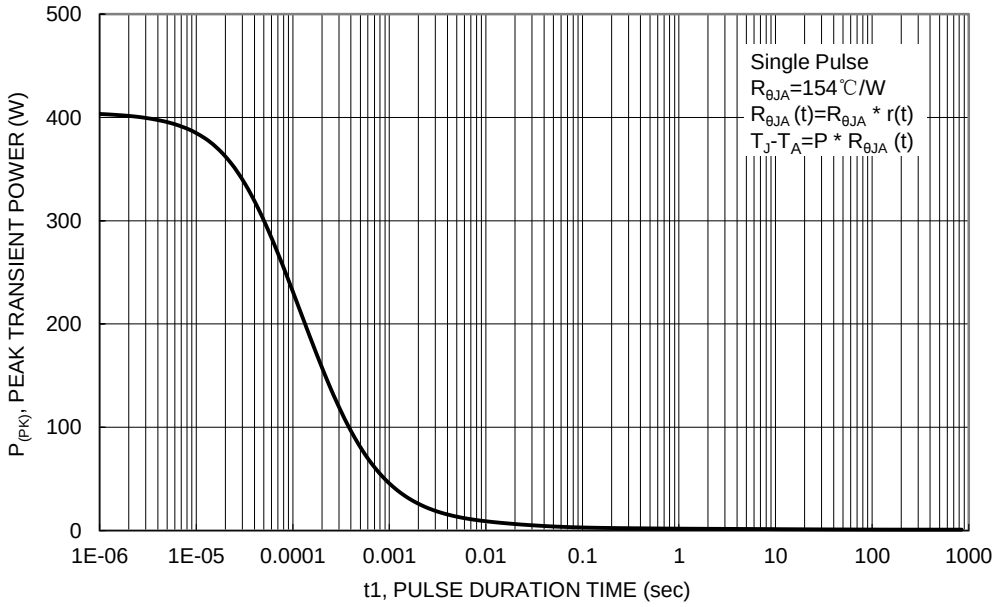


Figure 13. Single Pulse Maximum Power Dissipation

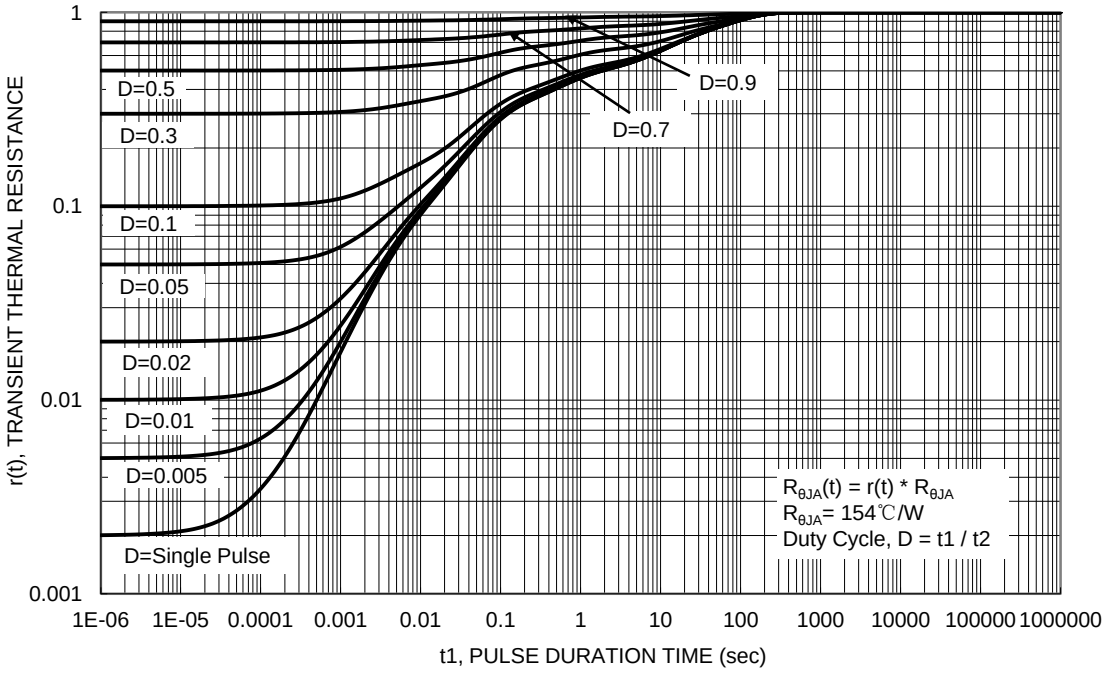
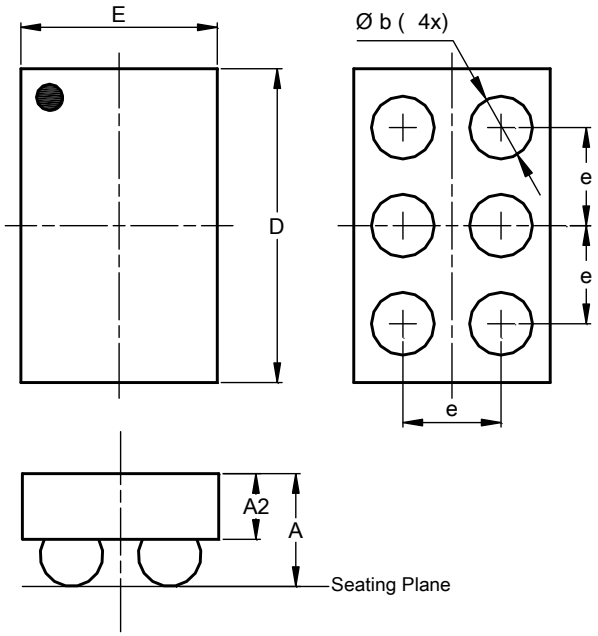


Figure 14. Transient Thermal Resistance

Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-WLB1510-6 (Type B)

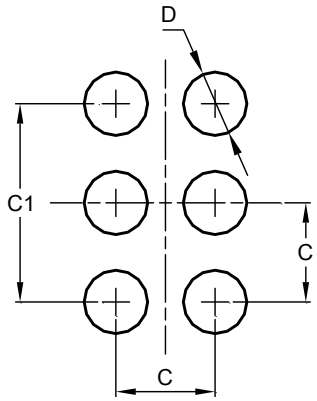


U-WLB1510-6 (Type B)			
Dim	**Min**	**Max**	**Typ**
A	--	0.60	--
A2	--	--	0.335
b	0.305	0.335	0.320
D	1.47	1.52	1.495
E	0.97	1.02	0.995
e	--	--	0.50
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-WLB1510-6 (Type B)



Dimensions	Value (in mm)
C	0.50
C1	1.00
D	0.30

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